



Customer Information Notification

201411008I

Issue Date: 28-Nov-2014

Effective Date: 26-Feb-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.

For detailed information we invite you to view this notification online



QUALITY

Management Summary

Various datasheet parameters of the TJA1044/TJA1057 Mantis products have been updated, improving robustness. There is no physical or design change associated with this.

Change Category

☐ Wafer Fab process	☐ Assembly Process	☐ Product Marking	☐ Design
☐ Wafer Fab materials	☐ Assembly Materials	☒ Electrical spec./Test coverage	☐ Mechanical Specification
☐ Wafer Fab location	☐ Assembly Location	☐ Test Location	☐ Packing/Shipping/Labeling

Improved Mantis robustness

Information Notification

Based on measurements we have been able to update various TJA1044/TJA1057 Mantis product datasheet parameters, improving robustness of these products. There are no physical or design changes at all made to these products. The improvements are:

- VESD IEC and HBM on pins CANH and CANL is increased from 6kV to 8kV
- The Absolute Maximum Rating (AMR) on pin Vcc is increased from 6V to 7V
- The datarate for the GT product versions is changed from 'beyond 1 Mbit/s' to 5 Mbit/s
- The maximum TXD and bus dominant time-out times are changed from 16 ms to 6.5 ms, enabling a faster system recovery
- The minimum bit rate is changed from 40 kbit/s to 25 kbit/s, allowing for lower communication rates to be used

For the parameter t_to(wake)bus typos in the parameter values have been corrected, bringing it back in line with the application note AH1308 which has always been correct. This application note in turn has been updated to bring it in line with the above-mentioned changes.

In addition a number of minor textual changes have been made to the datasheets, none of which impact the product's functionalities.

The revision history in the datasheets summarizes all the changes.

Note that apart from the above-mentioned improved robustness there is no impact to the product's functionality.

Why do we issue this Information Notification

These changes are made to ensure the correct information is in the datasheets of products TJA1044 and TJA1057.

Identification of Affected Products

Product identification does not change

Impact

There is no impact to the product's functionality, other than the improved product's robustness as specified by the parameters changed.

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Not applicable. There's no physical change to the products.

Remarks

Please use the link 'view online' above under the heading 'Additional information' to log in to the NXP e-PCN system you're subscribed to, in order to obtain the updated datasheets and application note from the tab 'Files'. These documents will also be published shortly on the NXP website (www.nxp.com).

Should you not be able to obtain these documents, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

In the NXP e-PCN system on the tab 'Products' you can see a list of your affected part numbers.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Kees van Hasselt
Position Quality Account Manager
e-mail address ivn.customer.service@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP's Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

[View Notification](#)

[Subscription](#)

[Support](#)

[NXP](#) | [Privacy Policy](#) | [Terms of Use](#)

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.